SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

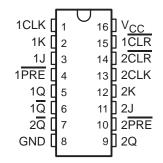
- Fully Buffered to Offer Maximum Isolation From External Disturbance
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS112A	50	6

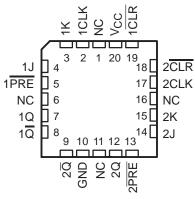
description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the J and K inputs meeting the setup-time requirements is transferred to the outputs on the negative-going edge of the clock pulse (CLK). Clock triggering occurs at a voltage level and is not directly related to the fall time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

SN54ALS112A . . . J PACKAGE SN74ALS112A . . . D OR N PACKAGE (TOP VIEW)



SN54ALS112A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The SN54ALS112A is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS112A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each flip-flop)

		INPUTS			OUTI	PUTS
PRE	CLR	CLK	J	K	Ø	Q
L	Н	Х	Χ	Х	Н	L
Н	L	X	Χ	X	L	Н
L	L	X	Χ	X	H [†]	н†
Н	Н	\downarrow	L	L	Q_0	\overline{Q}_0
Н	Н	\downarrow	Н	L	Н	L
Н	Н	\downarrow	L	Н	L	Н
Н	Н	\downarrow	Н	Н	Tog	ggle
Н	Н	Н	Χ	Χ	Q ₀	\overline{Q}_0

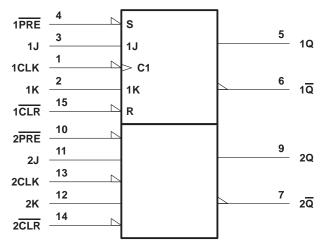
[†] The output levels in this configuration may not meet the minimum levels for V_{OH}. Furthermore, this configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.



SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

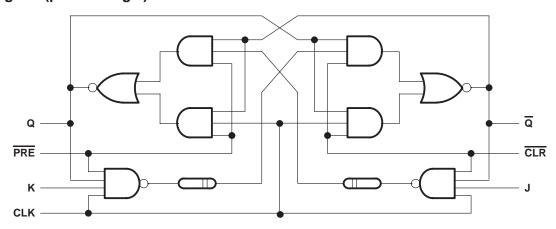
SDAS199A – APRIL 1982 – REVISED DECEMBER 1994

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54ALS112A	
SN74ALS112A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

SDAS199A - APRIL 1982 - REVISED DECEMBER 1994

recommended operating conditions

				54ALS11	2A	SN7	'4ALS11	2A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
ЮН	High-level output current				-0.4			-0.4	mA
loL	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		30	MHz
		PRE or CLR low	15			10			
t _W	Pulse duration	CLK high	20			16.5			ns
		CLK low	20			16.5			
	0	Data	25			22			ns
t _{su}	Setup time before CLK↓	PRE or CLR inactive	22			20			115
t _h	Hold time after CLK↓	Data	0			0		·	ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEST CONDITIONS		SN54ALS112A		2A	SN74ALS112A			UNIT
PA	PARAMETER TEST CONDITION		CNDITIONS	MIN TYPT MAX		MIN	TYP [†]	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.5			-1.5	V
Vон		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			V
Voi		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 4 \text{ mA}$ 0.25 $I_{OL} = 8 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL		VCC = 4.5 V						0.35	0.5	V
1.	J, K, or CLK	VCC = 5.5 V,	V _I = 7 V			0.1			0.1	mA
l _I	PRE or CLR	VCC = 5.5 V,	V = 7 V			0.2			0.2	IIIA
1	J, K, or CLK	V00 - 5 5 V	V _I = 2.7 V			20			20	
IН	PRE or CLR	V _{CC} = 5.5 V,	V = 2.7 V			40			40	μΑ
l	J, K, or CLK	V 55V	V ₂ 0.4.V			-0.2			-0.2	A
II∟	PRE or CLR	VCC = 5.5 V,	V _I = 0.4 V			-0.4			-0.4	mA
lo [‡]		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc		V _{CC} = 5.5 V,	See Note 1		2.5	4.5		2.5	4.5	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, l_{OS}. NOTE 1: ICC is measured with J, K, CLK, and PRE grounded, then with J, K, CLK, and CLR grounded.

SN54ALS112A, SN74ALS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

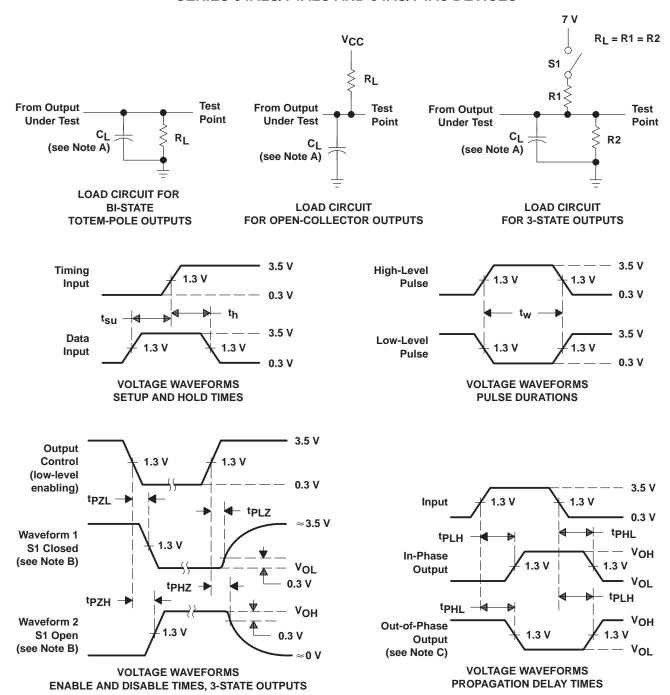
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍ C _I R _I T _Z	UNIT			
	, ,	,	SN54AL	S112A	SN74ALS112A		
			MIN	MAX	MIN	MAX	
f _{max}			25		30		MHz
t _{PLH}	PRE or CLR	Q or $\overline{\mathbb{Q}}$	3	26	3	15	ns
t _{PHL}	PRE OF CLR	QOIQ	4	23	4	18	115
^t PLH	CLK	Q or Q	3	23	3	15	ns
^t PHL	OLK	Q or Q	5	24	5	19	113

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finis	h MSL Peak Temp ⁽³⁾
84000022A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8400002EA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
8400002FA	OBSOLETE	CFP	W	16		None	Call TI	Call TI
JM38510/37103B2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
JM38510/37103BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN54ALS112AJ	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
SN74ALS112AD	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS112ADR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ALS112AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ALS112AN3	OBSOLETE	PDIP	N	16		None	Call TI	Call TI
SN74ALS112ANSR	ACTIVE	SO	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54ALS112AFK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54ALS112AJ	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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